

# Stressless Thermal Putty Gel / XK-G30

## Introduction

Syringes packaging, automated production, high temperature resistance, and 100% thermal curing putty. XK-G series is a silicone based, high performance thermal Gel, filling with a variety of high-performance ceramic powder, possessing the features of high thermal conductivity, insulation, infinite compression. XK-G30 stressless application especially for UAV.

## Features

- Especially for UAV design
- Excellent compressibility
- Low thermal resistance
- Best for north bridge IC

## Applications

- Consumer electronics/Automotive systems
- UAV/ Telecommunications
- Hand-set applications



	Unit	XK-G30	Method
Color		Blue	visual
Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	g/min	10	
Specific Gravity	g/cm <sup>3</sup>	3.1	ASTM D792
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Thermal Conductivity	W/mK	3.2	HOT DISK
Breakdown Voltage	KV/mm	10	ASTM D149
Dielectric Constant	1	8.0	ASTM D150
BLT Thickness	mm	0.09	ASTM D374
Application temperature	°C	-50~200	
shelf life	month	12	
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Coefficient of Thermal Expansion,	ppm/K	175	
Flammability	UL94	V-0	UL94